This is a pressfit tech thru hole with the following specs:

- Diameter of drilled hole: 1.15mm +/-0.02mm
- Diameter of finished plated through hole: 1.05 mm +/-0.05mm
- Hole Plating: 25-50 um Cu, 4-7.5 um Ni, 0.1-0.5 um Au (Electroless Ni/Immersion Au)

Note 11: All dimension in inches unless specified otherwise.

9. Impedance 50 Ohm for all single ended traces, and 100 Ohm for all differential traces.

8. FHS tolerances: +/-0.003" unless specified otherwise.

7. Interlayer Dielectric Thickness: as specified.

6. Silkscreen on both sides. Discard any writings smaller than 10 mils.

5. Electroless Nickel/Immersion Gold plating; apply solder mask.

4. 1 oz Copper for Layers: 1, 5, 6, 8, 9, 11, 12, and 16; 2 oz Copper for Layers: 2, 3, 14, and 15; 1/2 oz Copper for Layers 4, 7, 10, and 13.

3. Trace Width=6 mils on Layers 1, 4, 13, 16. Trace Width=4mils on Layers 7, 10. Min Crearance = 4 mils on signal layers, and 8 mils on power planes.

2. Board Thickness: 0.095"+-0.008".


0. All dimension in inches unless specified otherwise

Board Characteristics: 16-Layer Board

- Hole Plating: min 25 um Cu, 2.5-5 um Ni, 0.05-0.2 um Au (Electroless Ni/Immersion Au).
- Diameter of finished plated through hole: 0.6 mm +/-0.05mm
- Diameter of drilled hole: 0.7mm +/-0.02mm

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Note 15, 16

Note 10

Note 13

Note 9

Note 8

Note 7

Note 6

Note 5

Note 4

Note 3

Note 2

Note 1

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Do not increase size of thermal pads and their associated spike connections on 0.041" and 0.0413" diameter holes.

Via Fill and Overplate is required. Vias of this diameter must be completely filled with Peters PP-2795 or equivalent solids fill material,

Mill the Top and Bottom Edges of Board on the Solder Side to a thickness of 0.063" +/- 0.008".

IMPORTANT: Remove all non-functional inner layer pads for pins and vias.

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Note 11

Note 12

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This is a pressfit tech thru hole with the following specs:

- Diameter of drilled hole: 1.15mm +/-0.02mm
- Diameter of finished plated through hole: 1.05 mm +/-0.05mm
- Hole Plating: 25-50 um Cu, 4-7.5 um Ni, 0.1-0.5 um Au (Electroless Ni/Immersion Au)